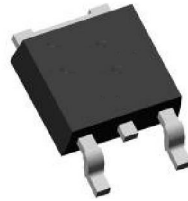
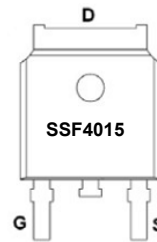


## Main Product Characteristics

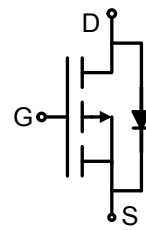
$V_{DSS}$	-40V
$R_{DS(on)}$	11m $\Omega$ (typ.)
$I_D$	-40A



TO-252 (DPAK)



Marking and Pin Assignment



Schematic Diagram

## Features and Benefits

- Advanced trench MOSFET process technology
- Ideal for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- High power and current handling capability
- 175°C operating temperature



## Description

The SSF4015 utilizes the latest processing techniques to achieve high cell density, low on-resistance and high repetitive avalanche rating. These features make this device extremely efficient and reliable for use in power switching applications and a wide variety of other applications.

## Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ ①	-40	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ ①	-28	
$I_{DM}$	Pulsed Drain Current②	-120	
$I_{SM}$	Pulsed Source Current (Body Diode)②	-120	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation③	75	W
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy @ L=0.1mH	40	mJ
$I_{AS}$	Single Pulse Avalanche Current @ L=0.1mH	28	A
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to + 175	$^\circ\text{C}$

## Thermal Resistance

Symbol	Characteristics	Value	Unit
R <sub>θJA</sub>	Junction-to-Ambient (t ≤ 10s) ④	14	°C/W
	Junction-to-Ambient (PCB mounted, steady-state) ④	40	°C/W
R <sub>θJC</sub>	Maximum Junction-to-Case⑤	2	°C/W

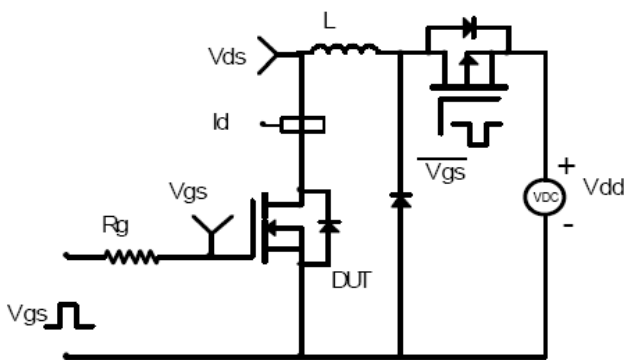
## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
BV <sub>DSS</sub>	Drain-to-Source breakdown voltage	-40	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
R <sub>DS(on)</sub>	Static Drain-to-Source on-resistance	—	11	15	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> = 12A
		—	14.3	—		T <sub>J</sub> = 125°C
		—	18.5	25		V <sub>GS</sub> =4.5V, I <sub>D</sub> = 8A
		—	23.6	—		T <sub>J</sub> = 125°C
V <sub>GS(th)</sub>	Gate threshold voltage	-1	—	-3	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA
I <sub>DSS</sub>	Drain-to-Source leakage current	—	—	-1	μA	V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V
		—	—	-5		T <sub>J</sub> = 55°C
I <sub>GSS</sub>	Gate-to-Source forward leakage	—	—	100	nA	V <sub>GS</sub> = 20V
	Gate-to-Source reverse leakage	—	—	-100		V <sub>GS</sub> = -20V
G <sub>(fs)</sub>	Forward transconductance	5	27	—	S	V <sub>DS</sub> = -5V, I <sub>D</sub> = -12.0A
Q <sub>g</sub>	Total gate charge	—	57.4	40	nC	I <sub>D</sub> = -20A, V <sub>DD</sub> = -12V, V <sub>GS</sub> = -10V
Q <sub>gs</sub>	Gate-to-Source charge	—	10.8	6		
Q <sub>gd</sub>	Gate-to-Drain("Miller") charge	—	11.9	15		
t <sub>d(on)</sub>	Turn-on delay time	—	15.2	—	ns	V <sub>DD</sub> = -18.8V, I <sub>D</sub> = -12.5A, R <sub>L</sub> = 1.50Ω, R <sub>G</sub> = 3.00Ω, V <sub>GS</sub> = -10V
t <sub>r</sub>	Rise time	—	23.7	—		
t <sub>d(off)</sub>	Turn-Off delay time	—	53.3	—		
t <sub>f</sub>	Fall time	—	12.7	—		
C <sub>iss</sub>	Input capacitance	—	5188	—	pF	V <sub>ds</sub> = -20V, V <sub>gs</sub> = 0V, f = 1MHZ
C <sub>oss</sub>	Output capacitance	—	376	—		
C <sub>rss</sub>	Reverse transfer capacitance	—	293	—		

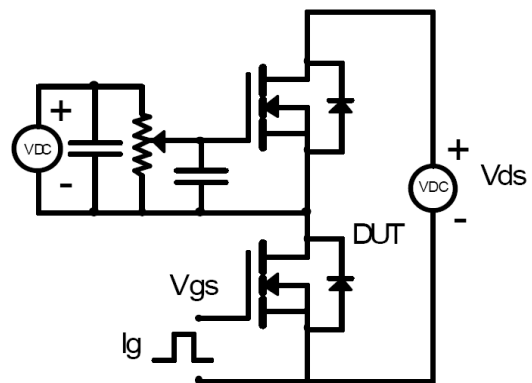
### Source-Drain Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Maximum Body-Diode Continuous Curren.	—	-40	—	A	
$V_{SD}$	Diode Forward Voltage	—	-0.74	1.2	V	$T_J=25^{\circ}\text{C}$ , $I_S=-1\text{A}$ , $V_{GS}=0\text{V}$

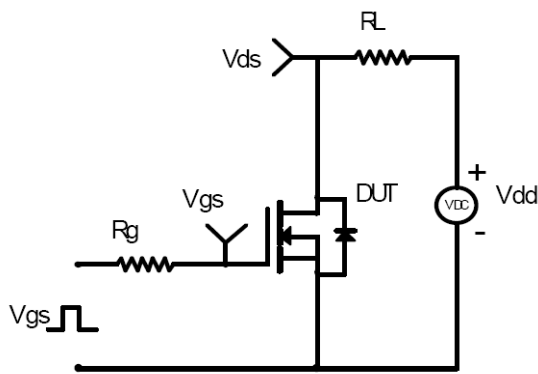
### Test Circuits and Waveforms



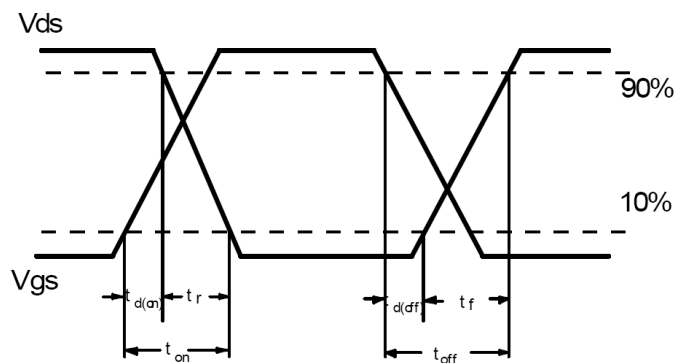
**E<sub>AS</sub> Test Circuit**



**Gate Charge Test Circuit**



**Switching Time Test Circuit**



**Switching Waveforms**

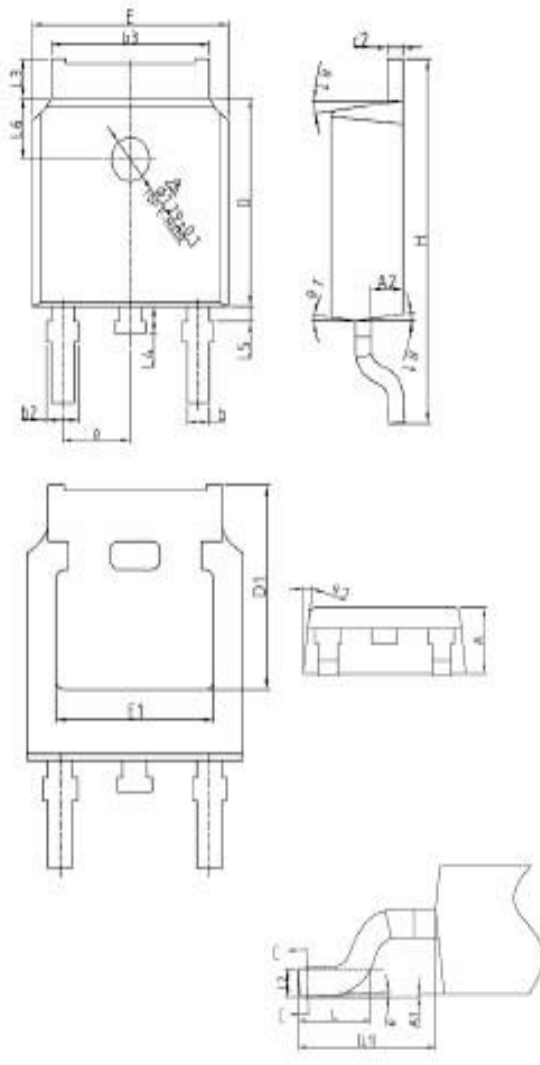
### Notes

- ① Calculated continuous current based on maximum allowable junction temperature.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation  $P_D$  is based on max. junction temperature, using junction-to-case thermal resistance.
- ④ The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^{\circ}\text{C}$

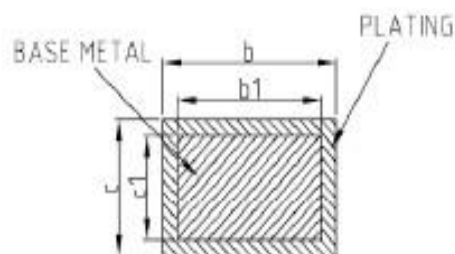
**Mechanical Data**

**TO-252E-2-M PACKAGE INFORMATION**

**Dimensions in Millimeters**



SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0	—	0.10
A2	0.90	1.01	1.10
b	0.72	—	0.85
b1	0.71	0.76	0.81
b2	0.72	—	0.90
b3	5.13	5.33	5.46
c	0.47	—	0.60
c1	0.46	0.51	0.56
c2	0.47	—	0.60
D	6.00	6.10	6.20
D1	5.25	—	—
E	6.50	6.60	6.70
E1	4.70	—	—
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90REF		
L2	0.51BSC		
L3	0.90	—	1.25
L4	0.60	0.80	1.00
L5	0.15	—	0.75
L6	1.80REF		
θ	0°	—	8°
θ 1	5°	7°	9°
θ 2	5°	7°	9°



**Ordering and Marking Information**

**Device Marking: SSF4015**

Package (Available)  
**TO-252/DPAK**  
 Operating Temperature  
 Range C : -55 to 175°C

**Devices per Unit**

**Option 1**

Package Type	Units/ Tube	Tubes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO-252	80	50	4000	10	40000

**Option 2**

Package Type	Units/ Tape	Tapes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO-252	2500	2	5000	7	35000

**Option 3**

Package Type	Units/ Tape	Tapes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO-252	2500	1	2500	10	25000